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UNITED STATES PATENT AND TRADEMARK OFFICE

1 In re the Application of: **Norio FUKASAWA et al.**

Serial No.: **09/766,656**

Group Art Unit: **2814**

Filed: **January 23, 2001**

Examiner: **To be assigned**

For: **METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,  
SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING THE DEVICE**

**SUPPLEMENTAL PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

February 21, 2002

Sir:

Prior to examination of this application, please amend the above-identified application as follows:

**IN THE CLAIMS:**

Please cancel claims 87-97 without prejudice or disclaimer and add new claims 98-110 as follows:

98. (New) A method for fabricating a semiconductor device comprising:  
a resin sealing step of loading a substrate on which semiconductor elements having protruding electrodes are formed to a mold, and supplying a sealing resin to positions of the protruding electrodes so as to form a first resin layer which seals the protruding electrodes and the substrate;  
a protruding electrode exposing step of exposing at least ends of the protruding electrodes from the first resin layer; and  
a separating step of cutting the substrate together with the first resin layer so that the semiconductor elements are separated from each other.